

1. Scope :

This specification applies to silicon zener double diodes Flip chips,
Device NO. SD-81269GF-A

2. Structure :

- 2-1. Planar type : NPN, Zener Double Diodes.
- 2-2. Electrodes :
Top side : SnAu Alloy.

3. Size :

- 3-1. *Chip size : 17.5 mils x 9.3 mils (0.445 mm x 0.235 mm).
- 3-2. Chip thickness : 2.8 ± 0.6 mils (0.070 ± 0.015 mm).
- 3-3. Top SnAu bonding pads : 4.2 mils x 5.5 mils x 2 (0.107 mm x 0.140 mm x 2).
- 3-4. The distance between dual bonding pad: 5.5 mils (0.140 mm).
- 3-5. Pattern drawing : Refer to the attached drawing.

*Including scribing line. The chip size is about $(0.420 \pm 0.015) \times (0.210 \pm 0.015)$ mm² after dicing.

4. Electrical characteristics (Ta = 25 °C)

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Reverse Leakage Current	I_R	$V_R=4V$ $E_e=0mW/cm^2$			100	nA
Zener Voltage	V_Z	$I_Z=5mA$ $E_e=0mW/cm^2$	6.4		7.6	V

